













ESD

TVS

TSS

MOV

GDT

PLED

# NTS4001NT1G

**Product specification** 





## Features

- 30V,300mA, RDS(ON) =1Ω@VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

# Application

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

BVDSS	RDSON	ID
30V	1Ω	300mA

# **Reference News**

PACKAGE OUTLINE	Pin Configuration	Marking
D	G	TĻ *
SOT-323	Ŝ	

# Absolute Maximum Ratings (TA=25 °C unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain- Source Voltage	30	V
Vgs	Gate- Source Voltage	±20	V
lo	Drain Current – Continuous (T <sub>A</sub> =25 °C)	300	mA
U	Drain Current – Continuous (T <sub>A</sub> =70 °C)	220	mA
Ідм	Drain Current – Pulsed <sup>1</sup>	1.0	A
5	Power Dissipation (Tc=25°C)	313	W
PD	Power Dissipation – Derate above 25 °C	2.5	Mw/℃
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C



### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit
Reja	Thermal Resistance Junction to ambient		400	°C /W

### Electrical Characteristics(TJ=25 °C , unless otherwise noted)

#### **Off Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	Vgs=0V , Id=250uA	30			V
△ BV <sub>DSS</sub> / △ T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 250 , ID=1mA		0.05		V/ C
	Drain- Source Leakage Current	Vps=30V , Vgs=0V , Tj=500			200	А
IDSS	Drain- Source Leakage Current	Vds=30V , Vgs=0V , Tj=850			400	А
lgss	Gate- Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±6	А

#### **On Characteristics**

P	Static Drain-Source On-Resistance	Vgs=10V , Id=0.3A		1.0	1.5	Ω
Rds(on)	Static Drain-Source On-Resistance	$V_{GS}$ =4 5V , I <sub>D</sub> =0.2A		1.3	2.3	32
VGS(th)	Gate Threshold Voltage		0.8	1.1	1.6	V
${}^{\vartriangle}V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$-\nabla GS - \nabla DS$ , $D - 250 uA$		3		mV/℃

#### **Dynamic and switching Characteristics**

С	Ciss	Input Capacitance		 23	
С	Coss	Output Capacitance	Vps=30V,Vgs=0V,F=1MHz	 16	 pF
С	Crss	Reverse Transfer Capacitance		 10	

#### **Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V . Force Current			300	mA
lsм	Pulsed Source Current				600	mA
Vsd	Diode Forward Voltage	$V_{GS}{=}0V$ , $I_{S}{=}0.2A$ , $T_{J}{=}25^{\circ}\!\!\!\mathbb{C}$			1.3	V

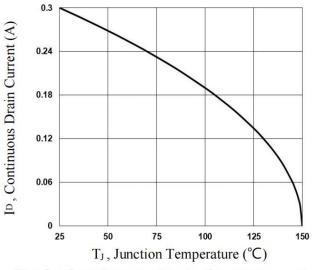
#### Note :

1.Repetitive Rating : Pulsed width limited by maximum junction temperature.

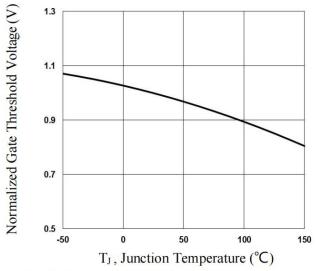
2 . The data tested by pulsed , pulse width  $\leq$  300 us , duty cycle  $\leq$  2%.

3. Essentially independent of operating temperature.











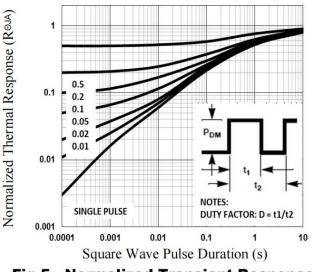
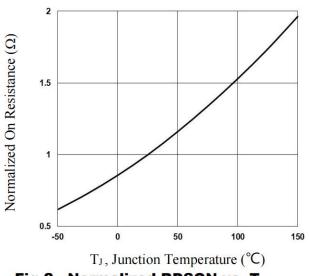
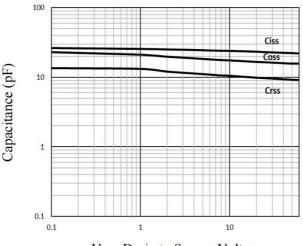


Fig.5 Normalized Transient Response







V<sub>DS</sub>, Drain to Source Voltage

**Fig.4 Capacitance Characteristics** 

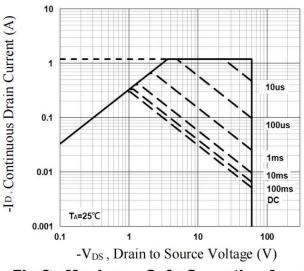
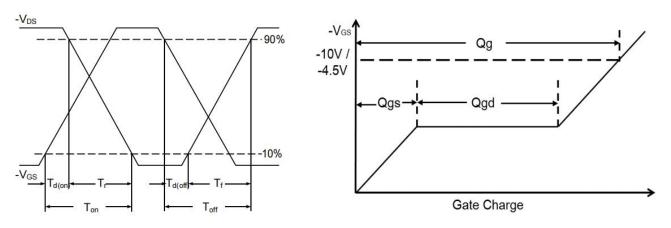


Fig.6 Maximum Safe Operation Area

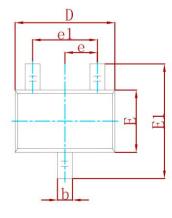


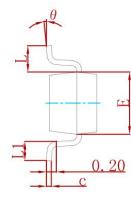


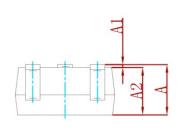




# PACKAGE MECHANICAL DATA

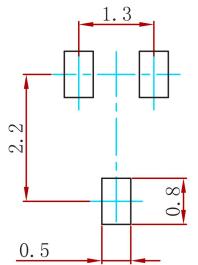






Symbol	Dimensions	In Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
С	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650	) TYP	0.026	6 TYP
e1	1.200	1.400	0.047	0.055
L	0.525	5 REF	0.021	REF
L1	0.260	0.460	0.010	0.018
9	0°	8°	0°	8°
	·			

# **Suggested Pad Layout**



Note:

1.Controlling dimension: in millimeters.

2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

# **REEL SPECIFICATION**

P/N	PKG	QTY
NTS4001NT1G	SOT-323	3000



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